

PAD AREA
 KEEP OUT AREA
RECOMMENDED PCB LAYOUT
 GENERAL TOLERANCE ± 0.05

NOTES:

1.MATERIAL:

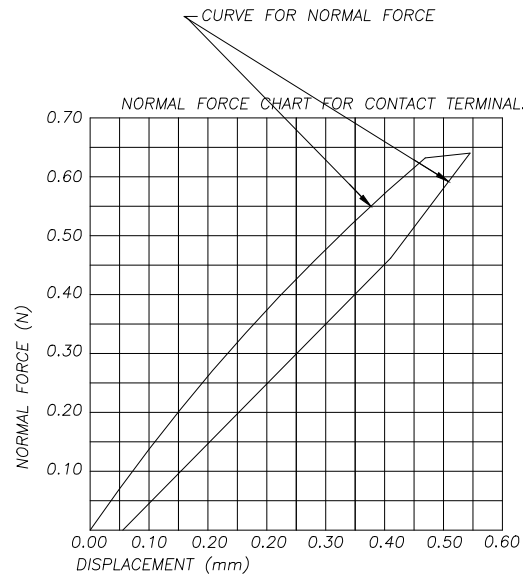
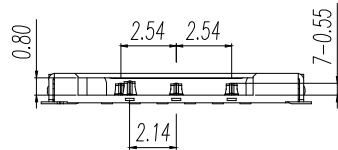
- 1.1 Housing:High Temperature Thermoplastic UL94V-0; Color Black.
- 1.2 Terminal:Copper Alloy,T=0.12mm.
- 1.3 Shell:Stainless Steel,T=0.20mm.

2.FINISH:

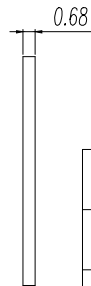
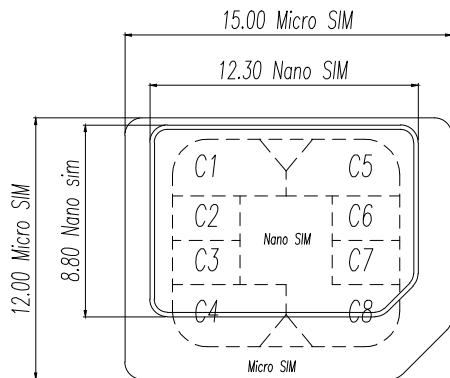
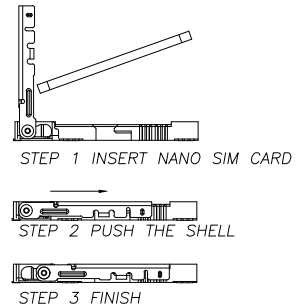
- 2.1 Terminal:Plated Gold on The Contact Area and Solder Tails
- 2.2 Peg:Plated Gold on the bottom of the Solder Tails, Tin Plated over all.

3.SPECIALITY:

- 3.1 Rated current:0.5A
- 3.2 Rated voltage:50V
- 3.3 Contact Resistance:80m Ω MAX
- 3.4 Insulation Resistance:100M Ω MIN 100V DC
- 3.5 Dielectric withstanding voltage: 100V AC.
- 3.6 Solder ability:245 $\pm 5^{\circ}$ C,5 ± 0.5 s.
- 3.7 Operating condition:Temperature: -40 $^{\circ}$ C~+85 $^{\circ}$ C Humidity: 80% R.H MAX



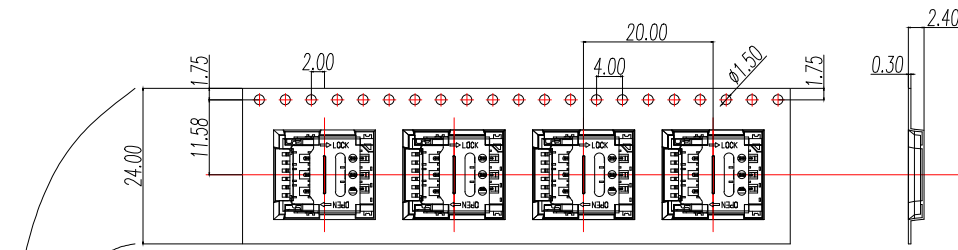
NANO SIM CARD	
Pin No.	NAME
C1	VCC OF SIM
C2	RST OF SIM
C3	CLK OF SIM
C5	GND OF SIM
C6	VPP OF SIM
C7	I/O OF SIM
C4/C8	N/A



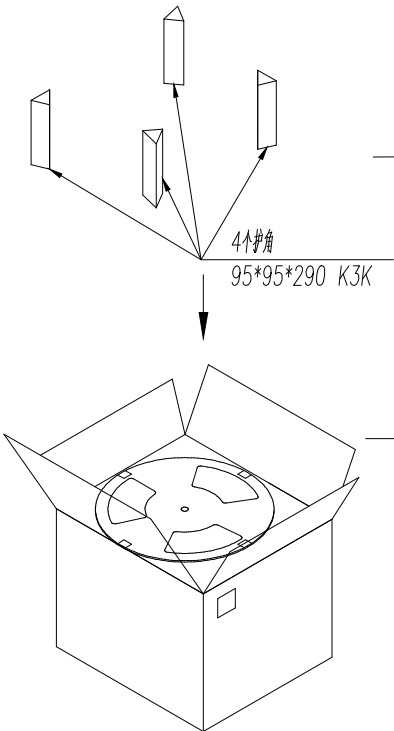
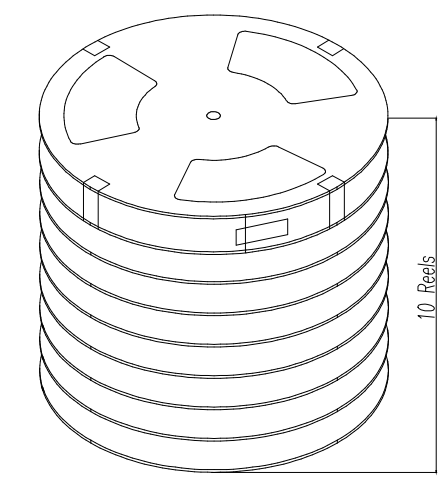
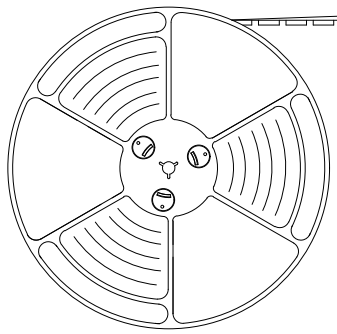
NO.	PART NAME	Q'TY	DESCRIPTION	NOTE
③	TERMINAL	6	C5210-EH,T=0.12	Au 3u" PLATING
②	BASE INSULATOR	1	LCP+GF30%	BLACK
①	SHELL	1	SUS304-H,T=0.15	AU/Ni PLATING

制图 DRAWN	变更内容 DESCRIPTION	日期 DATE	GENERAL TOLERANCE		审核 CHECK	批准 APPROVAL	单位 UNITS	比例 SCALE	张数 SHEET	页次 SHEET
			X ± 0.50	X' $\pm 2^{\circ}$						
			.X ± 0.20	.X' $\pm 1^{\circ}$			MM	1:1		
			.XX ± 0.10							

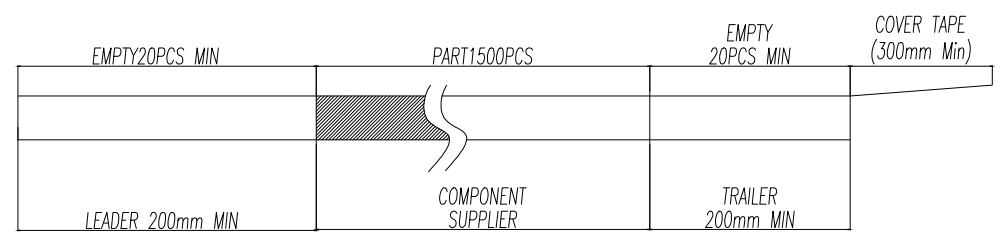
EMMA	料号 PART NO.	BX-SMN-1.4HJ	版本 REV.	A
EVA	品名 TITLE	6PIN 1.4H HINGE NANO SIM CARD CONN.	页次 SHEET	1/1
JADE	客户料号 CUTM.NO.		Bossie (博锡)	



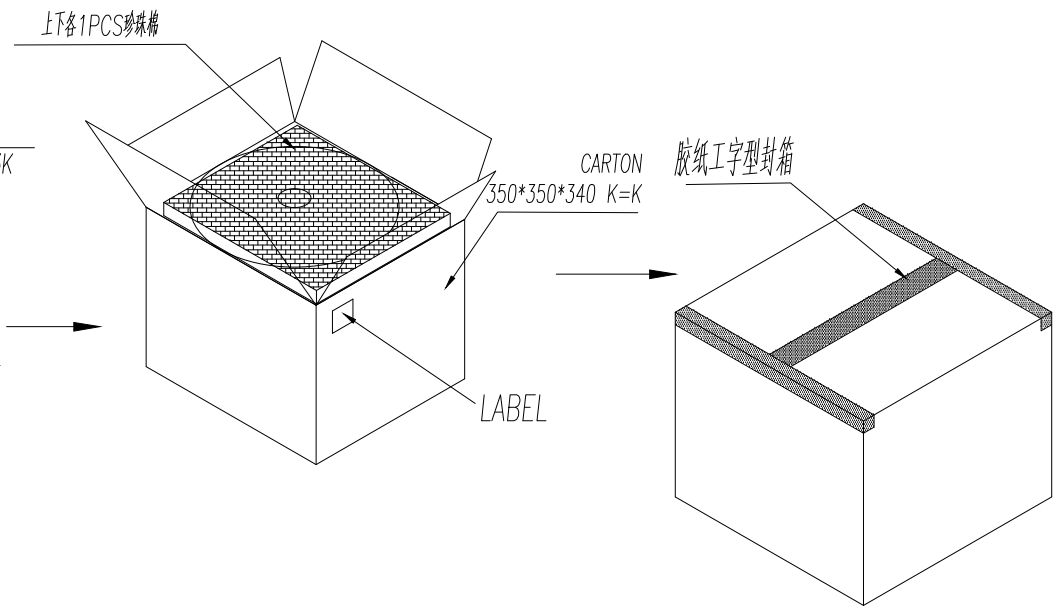
客户拉出方向
自粘上贴



- NOTES
1. NUMBER OF CONNECTORS:1500PCS/REEL
 2. LEAD TAPE LENGTH



3. QUANTITY: 15000PCS/CARTON



制图 DRAWN	变更内容 DESCRIPTION	日期 DATE	GENERAL TOLERANCE		制图 DRAWING	EMMA EVA JADE	料号 PART NO.	BX-SMN-1.4HJ	版本 REV.	A
			X.±0.50	X."±2"	审核 CHECK			6PIN 1.4H HINGE NANO SIM CARD CONN. 6脚	页次 SHEET	1/1
			.X±0.20	.X"±1"	批准 APPROVAL			客户料号 CUTM.NO.		
			.XX±0.10		单位 UNITS		MM	比例 SCALE	1:1	

